

WHAT IS CLAIMED IS:

33 1. A semiconductor device comprising:

a substrate;

5 a semiconductor chip mounted on one surface of said substrate, said semiconductor chip having an integrated circuit and bonding pads formed on a main surface thereof, said main surface of said semiconductor chip having a quadrilateral shape, said bonding pads being disposed along four sides of said main surface of said semiconductor chip;

10 a plurality of conductors being disposed on said one surface of said substrate to surround said semiconductor chip along the four sides thereof;

15 a plurality of bonding wires electrically connecting said bonding pads with tips of said plurality of conductors, respectively; and

a resin body sealing said semiconductor chip, said plurality of conductors and said plurality of bonding wires;

20 wherein a pitch between adjacent bonding pads increases in a direction toward four corners defined by the four sides of said main surface of said semiconductor chip.

2. A semiconductor device according to claim 1, wherein a largest pitch of the tips of the conductors of two adjacent conductors at the vicinity of each of the four corners of said semiconductor chip is less than twice a smallest pitch with respect to pitches of respective tips of said plurality of
25 conductors surrounding said semiconductor chip.

3. A semiconductor device according to claim 2, wherein
a relationship $(L) < 2 \times (W1) + (W2)$ exists, where (L) is an
allowable largest spacing at points of adjacent conductors,
(W1) is a smallest pitch of the adjacent conductors and (W2)
5 is a smallest width of the conductors.

4. A semiconductor device according to claim 3, wherein
said semiconductor chip is bonded to said substrate by a
thermosetting resin.

5. A semiconductor device according to claim 3, wherein
10 said substrate includes an insulating layer formed on said one
surface thereof.

6. A semiconductor device according to claim 3, wherein
said conductors are formed of a material whose principal
component is copper.